# INTEGRATED CIRCUITS

# DATA SHEET

# PTN3310/PTN3311

High-speed serial logic translators

Product data Supersedes data of 2002 Oct 24 2004 Feb 24





# **High-speed serial logic translators**

#### PTN3310/PTN3311

#### **FEATURES**

- Meets LVDS EIA-644 and PECL standards
- 2 pin-for-pin replacement input/output choices:
  - LVDS in, PECL out (PTN3310)
  - PECL in, LVDS out (PTN3311)
- Single +3.3 V supply voltage operation
- Available in 8-pin SO or TSSOP package
- Maximum throughput data rate of 800 Mbps typical

#### **APPLICATIONS**

- High-speed networking and telecom applications
  - ATM
  - SONET/SDH
  - Switches
  - Routers
  - Add-drop multiplexers

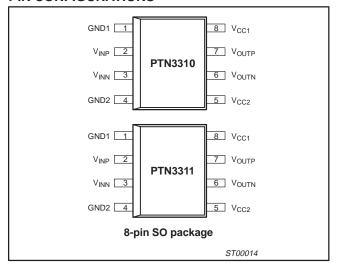
#### **GENERAL DESCRIPTION**

The High-Speed Serial Logic Translator provides a point solution that addresses the various interface logic requirements of Optical Transceiver Modules. The product offers a compact translation between LVDS and PECL high speed serial data lines. This provides the end users a simple way to mix or match Optical Transceiver ICs from various vendors to maximize desired performance and reduces the need to redesign interfaces to accommodate new Optical Transceiver ICs.

The High-Speed Serial Logic Translator comes in two translation choices to allow mixing LVDS and PECL input/outputs. The product is offered in a small, convenient, 8-pin package.

Figure 1 shows the High-Speed Serial Logic Translator Device in a typical high speed optical module application. Figure 2 shows the circuit block diagrams.

#### **PIN CONFIGURATIONS**



#### **PIN DESCRIPTIONS**

#### 8-pin SO and TSSOP package

Pin #	Symbol	Name and function
1, 4	GND1, GND2	Ground
2, 3	V <sub>INP</sub> , V <sub>INN</sub>	Differential inputs
5, 8	V <sub>CC1</sub> , V <sub>CC2</sub>	Supply voltage
6, 7	V <sub>OUTN</sub> , V <sub>OUTP</sub>	Differential outputs

#### ORDERING INFORMATION

Type number	Package	Package									
Type number	Name	Description	Version								
PTN3310D	SO8	Plastic small-outline package; 8 leads; body width 3.9 mm	SOT96-1								
PTN3311D	SO8	Plastic small-outline package; 8 leads; body width 3.9 mm	SOT96-1								
PTN3310DP	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm	SOT505-1								
PTN3311DP	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm	SOT505-1								

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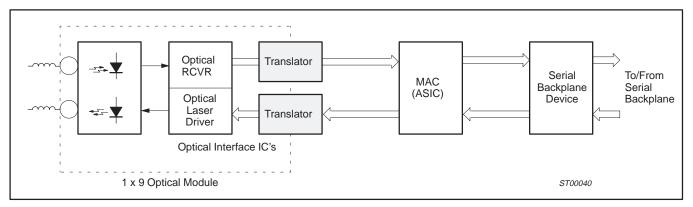


Figure 1. High-Speed Serial Logic Translators in Optical Module Application

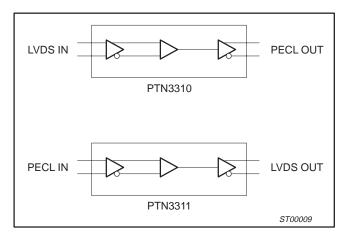


Figure 2. High-Speed Serial Logic Translator Block Diagrams

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Limits	Unit
V <sub>CC</sub>	Supply voltage	-0.3 to +4.0	V
VI	LVDS receiver input voltage	-0.3 to +5.5	V
Vo	LVDS driver output voltage	-0.3 to +5.5	V
t <sub>SC</sub>	LVDS output short circuit duration	continuous	
Tj	Maximum junction temperature	+150	°C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C
ESD <sub>HBM</sub>	Electrostatic discharge (Human Body Model, 1.5 kΩ, 100 pF)	>2	kV
ESD <sub>MM</sub>	Electrostatic discharge (Machine Model, 0 kΩ, 200 pF)	>200	V

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply voltage	3.0	3.6	V
T <sub>amb</sub>	Operating ambient temperature range in free air	-40	+85	°C
V <sub>CCN</sub>	Power supply noise voltage	_	100	$mV_{PP}$

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#### DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
General				•		
V <sub>CC</sub>	Supply voltage		3.0	3.3	3.6	V
I <sub>CC</sub>	Power supply current	PTN3311	-	12	20	mA
I <sub>EE</sub>	Power supply current	PTN3310	-	13	20	mA
PECL inpu	uts (PTN3311)					
V <sub>IH</sub>	Input HIGH voltage <sup>1</sup>		2.135	_	2.420	V
V <sub>IL</sub>	Input LOW voltage <sup>1</sup>		1.490	-	1.825	V
II	Input current	V <sub>IN</sub> = V <sub>CC</sub> or GND	-	-	±10	μΑ
LVDS inpu	its (PTN3310)	•		•	•	•
V <sub>ID</sub>	Minimum differential input signal amplitude		100	_	_	mV
I <sub>IN</sub>	Input current <sup>2</sup>	V <sub>IN</sub> = 0 V	-	Ī-	20	μΑ
		$V_{IN} = V_{CC}$	-	Ī-	20	μΑ
PECL out	outs (PTN3310)			•	•	•
V <sub>OH</sub>	Output HIGH voltage <sup>1</sup>		2.275	2.345	2.420	V
V <sub>OL</sub>	Output LOW voltage <sup>1</sup>		1.490	1.595	1.680	V
C <sub>L</sub>	Output load capacitance		-	5	-	pF
LVDS out	outs (PTN3311); $R_L$ = 100 $\Omega$	•		•		
V <sub>OD</sub>	Output differential voltage		250	350	450	mV
ΔV <sub>OD</sub>	Steady-state difference in output differential voltage between complementary output states		-	-	50	mV
Vos	Offset voltage		1.125	1.250	1.375	V
ΔV <sub>OS</sub>	Steady-state difference in offset voltage between complementary output states		-	-	50	mV
Ios	Output short-circuit current	outputs mutually shorted	-	-	12	mA
		output shorted to GND	-	-	24	mA
C <sub>L</sub>	Output load capacitance		-	5	<b>-</b>	pF

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These values are for V<sub>CC</sub> = 3.3 V; PECL level specifications are referenced to V<sub>CC</sub> and will track 1:1 with variation of V<sub>CC</sub>.
 Power supply either on or off.

#### **AC ELECTRICAL CHARACTERISTICS**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
General		•				•
f <sub>MAX</sub>	Maximum throughput data rate		655	800	<u> </u>	Mbps
	Clock output skew, part-to-part		-	100	-	ps
t <sub>SKEW</sub>	Clock output pulse skew			50	-	ps
± /±	Propagation delay input (differential) to output			1	3	ns
t <sub>PLH</sub> /t <sub>PHL</sub>	Propagation delay input (single-ended) to output		-	1	3	ns
PECL out	puts (PTN3310)	-				
t <sub>r</sub> /t <sub>f</sub>	Output rise and fall times at 20% and 80% intersects		_	200	300	ps
LVDS out	outs (PTN3311); $R_L = 100 \Omega$ ; $C_L = 5 pF$	•				
t <sub>TLH</sub>	Transition time LOW to HIGH	$R_L = 100 \Omega; C_L = 5 pF$		500	650	ps
t <sub>THL</sub>	Transition time HIGH to LOW	$R_L = 100 \Omega; C_L = 5 pF$	-	500	650	ps
V <sub>OSS</sub>	Peak-to-peak switching offset voltage	Measured between two matched 49.9 Ω load resistors; 5 pF load capacitance	-	-	150	mV

#### LVDS REFERENCE MEASUREMENT CONFIGURATION

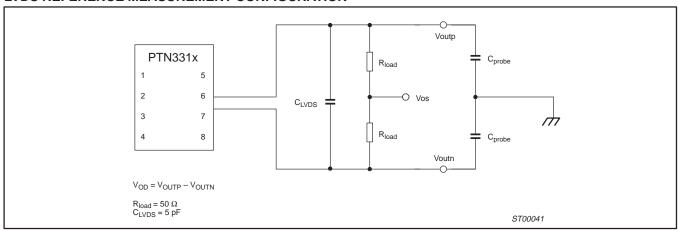


Figure 3.

The above diagram shows the test set-up used when evaluating LVDS outputs. According to the TIA-EIA-644 Standard, the maximum lumped capacitance test load should be 5 pF. However, by using probes or cables to observe the signal, additional capacitance is added, which has an effect on the rise and fall times.  $C_{probe}$  represents any capacitance caused by the use of probes or cables. Assuming balanced loading and balanced output drivers, the total effective capacitance seen by the part is:

$$C_{Eff} = C_{LVDS} + \frac{1}{2} C_{probe}$$

To correctly account for the effects of  $C_{\text{probe}}$ , the following formula should be used:

$$\Delta t = \frac{5 \text{ pF}}{C_{\text{Eff}}} \Delta t_{\text{measured,}}$$

Where  $\Delta t$  is the 20%–80% rise/fall time.

To avoid the use of additional calculation of the measured results, a different approach could be taken; however, the value of  $C_{\text{probe}}$  has to be known in advance. In that case, the value of  $C_{\text{LVDS}}$  can be chosen such that the sum of the capacitances equals 5 pF, i.e.:

$$C_{LVDS} + \frac{1}{2} C_{probe} = 5 pF$$

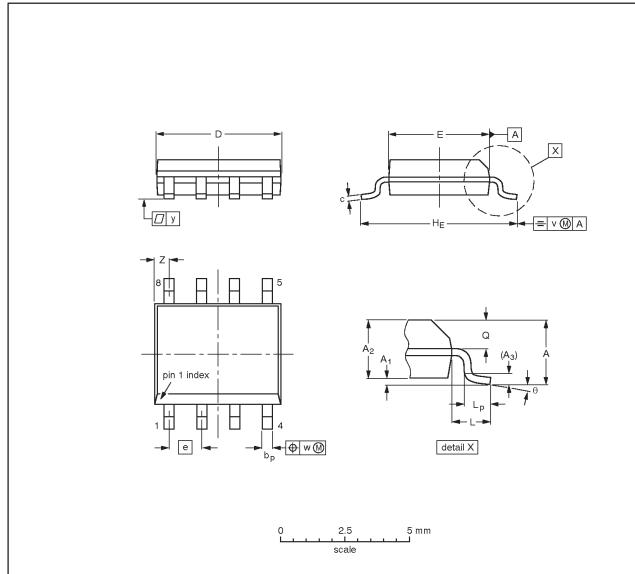
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# High-speed serial logic translators

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#### SO8: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.20 0.19	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	o°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.
- 2. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

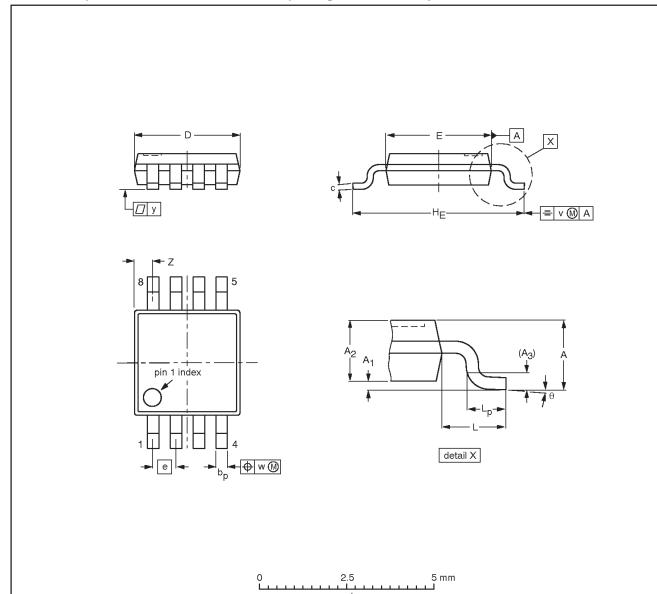
OUTLINE		EUROPEAN	ISSUE DATE				
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT96-1	076E03	MS-012				<del>99-12-27</del> 03-02-18	

# High-speed serial logic translators

# PTN3310/PTN3311

#### TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm

SOT505-1



#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bp	С	D <sup>(1)</sup>	E <sup>(2)</sup>	e	HE	L	Lp	v	w	у	Z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.45 0.25	0.28 0.15	3.1 2.9	3.1 2.9	0.65	5.1 4.7	0.94	0.7 0.4	0.1	0.1	0.1	0.70 0.35	6° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT505-1						<del>-99-04-09-</del> 03-02-18	

# High-speed serial logic translators

# PTN3310/PTN3311

#### **REVISION HISTORY**

Rev	Date	Description
_3	20040224	Product data (9397 750 12943). Supersedes data of 2002 Oct 24 (9397 750 10628).  Modifications:
		Corrected package outline version from SOT505-2 to SOT505-1 in Ordering information table and Package outline sections.
_2	20021024	Product data (9397 750 10628). ECN 853-2362 28701 dated 06 August 2002. Supersedes data of 2001 Jun 19 (9397 750 08511).
_1	20010619	Product data (9397 750 08511).

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#### Data sheet status

Level	Data sheet status [1]	Product status <sup>[2] [3]</sup>	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development.  Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Date of release: 02-04

Document order number: 9397 750 12943

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<sup>[3]</sup> For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.